

Amendments to the Claims:

Claims 1-16 (Cancelled).

17. (New) A semiconductor device comprising:

a semiconductor substrate having a first-side surface, a second-side surface, and a via hole penetrating said semiconductor substrate from said first-side surface to said second-side surface;

an electrode on said first-side surface of said semiconductor substrate and arranged so that a portion of said electrode extends to said second-side surface of said semiconductor substrate through said via hole; and

a photosensitive resin formed over said first-side surface of said semiconductor substrate so as to cover at least a portion of said first-side surface including an aperture of said via hole, an area of said at least a portion being larger than an area of said aperture of said via hole, said photosensitive resin filling in said via hole to a depth less than an entire depth of said via hole.

18. (New) The semiconductor device of claim 17, further comprising:

a reverse-side electrode formed on said second-side surface of said semiconductor substrate;

an adhesive metal formed on a surface of said reverse-side electrode such that said adhesive metal fills said via hole from an aperture of said via hole at said second-side surface to said photosensitive resin filled in said via hole; and

an assembly substrate attached to said reverse-side electrode via said adhesive metal.

19. (New) The semiconductor device of claim 18, wherein a main ingredient of said photosensitive resin is silicone resin or epoxy resin.

20. (New) The semiconductor device of claim 18, wherein a viscosity of said photosensitive resin at 25°C is in a range of 70 mPa·s to 600 mPa·s.

21. (New) The semiconductor device of claim 17, wherein a main ingredient of said photosensitive resin is silicone resin or epoxy resin.

22. (New) The semiconductor device of claim 17, wherein a viscosity of said photosensitive resin at 25°C is in a range of 70 mPa·s to 600 mPa·s.

23. (New) The semiconductor device of claim 17, further comprising an adhesive metal formed over said second-side surface of said semiconductor substrate such that said adhesive metal fills a portion of said via hole from an aperture of said via hole at said second-side surface to said photosensitive resin filled in said via hole.